ME TBUS PST 1,5/ 5-3,81 THRR32 - Contact strip

2914369

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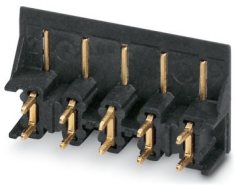
Pin strip for soldering into the PCB, for contacting in DIN rail bus connectors



Your advantages

- Space-saving installation under the housing in the DIN rail
- Contact design enables electronics modules to be easily snapped on
- Power supply and communication without additional wiring

Commercial data

Item number	2914369
Packing unit	440 pc
Minimum order quantity	440 pc
Note	Made to order (non-returnable)
Product key	ACHACZ
GTIN	4046356051057
Weight per piece (including packing)	2.02 g
Weight per piece (excluding packing)	2 g
Country of origin	DE

Technical data

Product properties

Product type	Pin strip
Number of positions	5
Pitch	3.81 mm
Pin layout	Linear pinning
Solder pins per potential	1

Electrical properties

Properties

Nominal current I_N	6 A
Nominal voltage U_N	125 V
Contact resistance	2.34 mΩ
Rated voltage (III/3)	125 V
Rated surge voltage (III/3)	2.5 kV
Rated voltage (III/2)	125 V
Rated surge voltage (III/2)	2.5 kV

Mounting

Mounting type	THR soldering / wave soldering
Pin layout	Linear pinning

Processing notes

Process	Reflow/wave soldering
Moisture Sensitive Level	MSL 1
Classification temperature T_c	260 °C
Solder cycles in the reflow	3

Material specifications

Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	gold-plated

Material data - housing

Color (Housing)	black (9005)
Insulating material	PA
Insulating material group	I
CTI according to IEC 60112	600
Flammability rating according to UL 94	V0
Temperature for the ball pressure test according to EN 60695-10-2	125 °C

Notes

Recommendation	Material of contact pads for bus connector, galvanic gold (hard gold)
Details for soldering processes	Processing using reflow processes in compliance with IEC 60068-2-58 or DIN EN 61760-1 (latest version) Moisture Sensitive Level (MSL) = 1 according to IPC/JEDEC J-STD-020-C

Dimensions

Pitch	3.81 mm
Width [w]	10.8 mm
Solder pin length [P]	2.05 mm
Pin dimensions	0.6 x 0.6 mm

Mechanical tests

Visual inspection

Specification	IEC 60512-1-1:2002-02
Result	Test passed

Dimension check

Specification	IEC 60512-1-2:2002-02
Result	Test passed

Insertion and withdrawal forces

Result	Test passed
No. of cycles	25
Insertion strength per pos. approx.	2.18 N
Withdraw strength per pos. approx.	1.38 N

Polarization and coding

Specification	IEC 60512-13-5:2006-02
Result	Test passed

Electrical tests

Thermal test | Test group C

Specification	IEC 60512-5-1:2002-02
Tested number of positions	5

Air clearances and creepage distances |

Specification	IEC 60664-1:2007-04
Insulating material group	I
Rated insulation voltage (III/3)	125 V
Rated surge voltage (III/3)	2.5 kV
minimum clearance value - non-homogenous field (III/3)	1.5 mm
minimum creepage distance (III/3)	1.9 mm
Rated insulation voltage (III/2)	125 V

Rated surge voltage (III/2)	2.5 kV
minimum clearance value - non-homogenous field (III/2)	1.5 mm
minimum creepage distance (III/2)	1.5 mm

Environmental and real-life conditions

Durability test

Specification	IEC 60512-9-1:2010-03
Impulse withstand voltage at sea level	2.5 kV
Contact resistance R_1	2.34 mΩ
Contact resistance R_2	2.27 mΩ
Insertion/withdrawal cycles	25

Climatic test

Specification	DIN 50018:2013-05
Corrosive stress	0.2 dm^3 SO_2 on 300 dm^3/40 °C/1 cycle
Thermal stress	100 °C/168 h
Power-frequency withstand voltage	1.39 kV

Vibration test

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.35 mm (10 Hz ... 60.1 Hz)
Acceleration	5g (60.1 Hz ... 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis (pos. and neg.)

Shocks

Specification	IEC 60068-2-27:2008-02
Pulse shape	Semi-sinusoidal
Acceleration	30g
Shock duration	18 ms
Test directions	X-, Y- and Z-axis (pos. and neg.)

Ambient conditions

Ambient temperature (storage/transport)	-40 °C ... 55 °C
Relative humidity (storage/transport)	30 % ... 70 %
Ambient temperature (assembly)	-5 °C ... 100 °C
Ambient temperature (operation)	-40 °C ... 105 °C (dependent on the derating curve)

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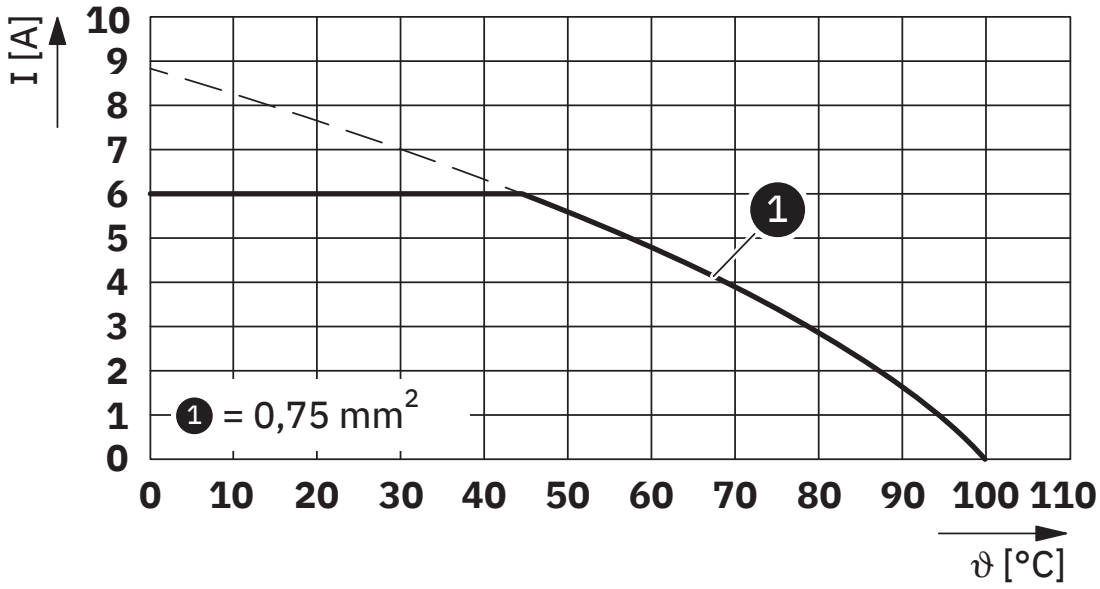
Packaging specifications

Type of packaging	32 mm wide tape
[W] tape width	32 mm
[W2] coil overall dimension	38.4 mm
[A] coil diameter	330 mm
Outer packaging type	Transparent-Bag

Drawings

Diagram



Type: ME TBUS PST 1,5/ 5-3,81 ...

Classifications

ECLASS

ECLASS-13.0	27460201
ECLASS-15.0	27460201

ETIM

ETIM 10.0	EC002637

UNSPSC

UNSPSC 21.0	39121400

Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions

China RoHS

Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits

EU REACH SVHC

REACH candidate substance (CAS No.)	No substance above 0.1 wt%

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